

**PINGWEI ENTERPRISE** 

# ABS202 THRU ABS210

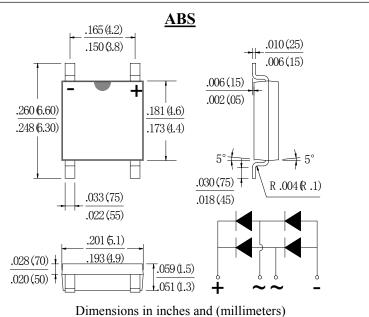
#### SINGLE PHASE2.0AMPS. GLASS PASSIVATED BRIDGE RECTIFIERS

### FEATURE

- . Glass passivated junction.
- . Ideal for printed circuit board.
- . Reliable low cost construction utilizing molded plastic technique.
- . High surge current capability.
- . High temperature soldering guaranteed:
- $260^{\circ}$ C/10 seconds at terminals.
- . UL Recognized File # E338195.

## MECHANICAL DATA

- Case Material: "Green" Molding compound, UL flammability classification rating 94V-0, "Free halogen"
- . Moisture sensitivity level:level 2a,per J-STD-020
- . Polarity:Polarity as marked on the body
- . Weight: 0.10g (approximately)



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at  $25^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYM BOL	ABS202	ABS204	ABS206	ABS208	ABS210	units
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	140	280	420	560	700	V
Maximum DC blocking Voltage	V <sub>DC</sub>	200	400	600	800	1000	V
Maximum Average Forward rectified Current @ $T_A=40^{\circ}C$	I <sub>F(AV)</sub>	2.0					A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I <sub>FSM</sub>	55					A
Maximum Instantaneous $@$ I <sub>F</sub> =2.0A DCForward Voltage $@$ I <sub>F</sub> = 1.0A DC	V <sub>F</sub>	1.1 0.95					v
Maximum DC Reverse Current $@T_J = 25^{\circ}C$ at rated DC blocking voltage $@T_J = 125^{\circ}C$	IR	5.0 100.0					μΑ
I <sup>2</sup> t Rating for Fusing (t < 8.3ms)	I <sup>2</sup> t	12.5					A <sup>2</sup> Sec
Typical Junction Capacitance Per Leg (Note1)	CJ	25					pF
Typical Thermal Resistance (Note2)	R <sub>JC</sub> R <sub>JA</sub>	18 50					°C /W
Storage Temperature	T <sub>STG</sub>	-55 to +150					°C
Operating Junction Temperature	TJ	-55 to +150					°C

#### Note:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc

2. Thermal resistance junction to case, lead and ambient in accordance with JESD-51.

Unit mounted on glass-epoxy substrate with 1oz/ft2\_20x20 mm copper pad per pin with heatsink

### RATING AND CHARACTERISTIC CURVES (ABS202 THRU ABS210)

